

SERIAL INTERFACE CODEC/FILTER WITH RECEIVE POWER AMPLIFIER

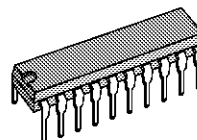
- COMPLETE CODEC AND FILTERING SYSTEM INCLUDING :
 - Transmit high-pass and low-pass filtering.
 - Receive low-pass filter with sin x/x correction.
 - Active RC noise filter.
 - μ -law or A-law compatible CODER and DECODER.
 - Internal precision voltage reference.
 - Serial I/O interface.
 - Internal auto-zero circuitry.
 - Receive push-pull power amplifiers.
- μ -LAW ETC5064
- A-LAW ETC5067
- MEETS OR EXCEEDS ALL D3/D4 AND CCITT SPECIFICATIONS.
- ± 5 V OPERATION.
- LOW OPERATING POWER-TYPICALLY 70 mW
- POWER-DOWN STANDBY MODE-TYPICALLY 3 mW
- AUTOMATIC POWER DOWN
- TTL OR CMOS COMPATIBLE DIGITAL INTERFACES
- MAXIMIZES LINE INTERFACE CARD CIRCUIT DENSITY
- 0°C TO 70°C OPERATION: ETC5064/67
- -40°C TO 85°C OPERATION: ETC5064-X/67-X

DESCRIPTION

The ETC5064 (μ -law), ETC5067 (A-law) are monolithic PCM CODEC/FILTERS utilizing the A/D and D/A conversion architecture shown in the Block Diagrams and a serial PCM interface. The devices are fabricated using double-poly CMOS process.

Similar to the ETC505X family, these devices feature an additional Receive Power Amplifier to provide push-pull balanced output drive capability. The receive gain can be adjusted by means of two external resistors for an output level of up to ± 6.6 V across a balanced 600 Ω load.

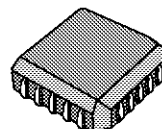
Also included is an Analog Loopback switch and TSx output.



DIP20
(Plastic) N

ORDERING NUMBERS:

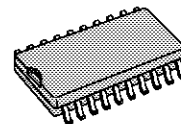
ETC5064N
ETC5064N-X
ETC5067N
ETC5067N-X



PLCC20
FN

ORDERING NUMBERS:

ETC5064FN
ETC5064FN-X
ETC5067FN
ETC5067FN-X



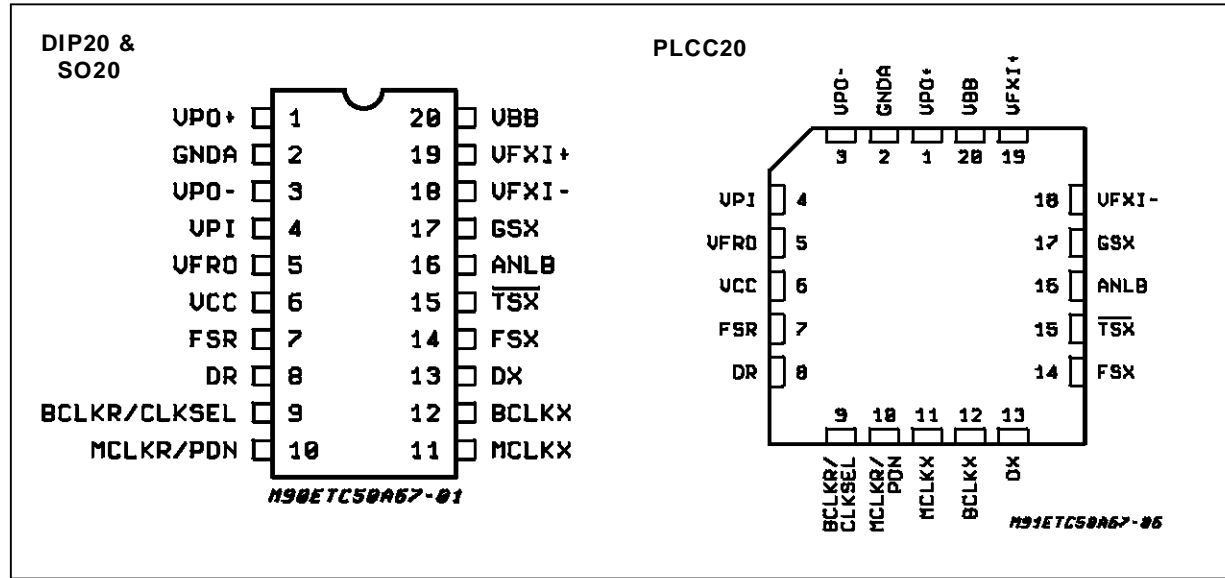
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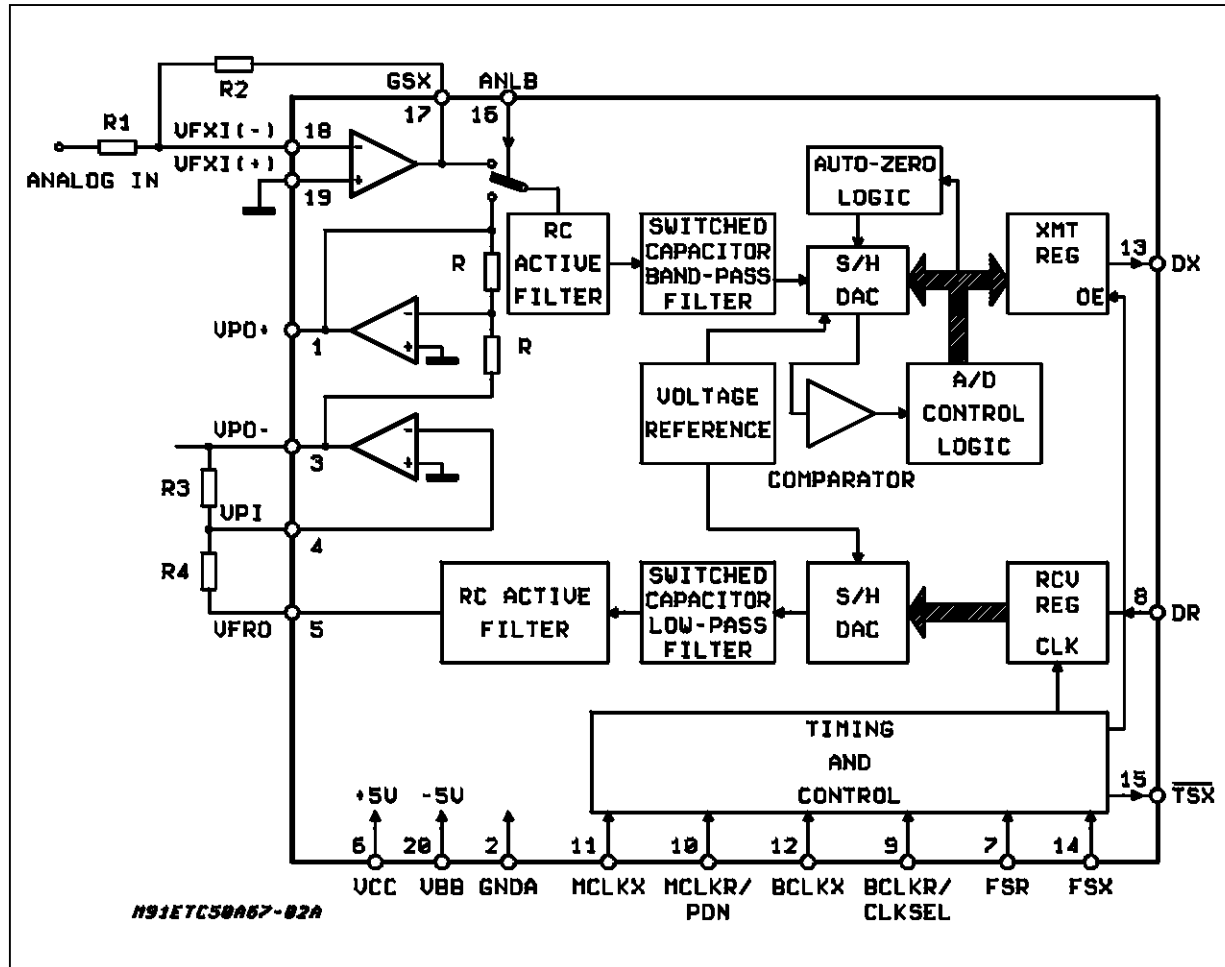
ETC5064D
ETC5064D-X
ETC5067D
ETC5067D-X

ETC5064 - ETC5064-X - ETC5067 - ETC5067-X

PIN CONNECTIONS (Top views)



BLOCK DIAGRAM (ETC5064 - ETC5064-X - ETC5067 - ETC5067-X)



PIN DESCRIPTION

Name	Pin Type (*)	N	Description
VPO ⁺	O	1	The Non-inverting Output of the Receive Power Amplifier
GNDA	GND	2	Analog Ground. All signals are referenced to this pin.
VPO ⁻	O	3	The Inverting Output of the Receive Power Amplifier
VPI	I	4	Inverting Input to the Receive Power Amplifier. Also powers down both amplifiers when connected to V _{BB} .
VF _R O	O	5	Analog Output of the Receive Filter.
V _{CC}	S	6	Positive Power Supply Pin. V _{CC} = +5V ±5%
FS _R	I	7	Receive Frame Sync Pulse which enable BCLK _R to shift PCM data into D _R . FS _R is an 8KHz pulse train. See figures 1 and 2 for timing details.
D _R	I	8	Receive Data Input. PCM data is shifted into D _R following the FS _R leading edge
BCLK _R /CLKSEL	I	9	The bit Clock which shifts data into D _R after the FS _R leading edge. May vary from 64KHz to 2.048MHz. Alternatively, may be a logic input which selects either 1.536MHz/1.544MHz or 2.048MHz for master clock in synchronous mode and BCLK _X is used for both transmit and receive directions (see table 1). This input has an internal pull-up.
MCLK _R /PDN	I	10	Receive Master Clock. Must be 1.536MHz, 1.544MHz or 2.048MHz. May be asynchronous with MCLK _X , but should be synchronous with MCLK _X for best performance. When MCLK _R is connected continuously low, MCLK _X is selected for all internal timing. When MCLK _R is connected continuously high, the device is powered down.
MCLK _X	I	11	Transmit Master Clock. Must be 1.536MHz, 1.544MHz or 2.048MHz. May be asynchronous with MCLK _R .
BCLK _X	I	12	The bit clock which shifts out the PCM data on D _X . May vary from 64KHz to 2.048MHz, but must be synchronous with MCLK _X .
D _X	O	13	The TRI-STATE [®] PCM data output which is enabled by FS _X .
FS _X	I	14	Transmit frame sync pulse input which enables BCLK _X to shift out the PCM data on D _X . FS _X is an 8KHz pulse train. See figures 1 and 2 for timing details.
$\overline{\text{TS}}_X$	O	15	Open drain output which pulses low during the encoder time slot. Must to be grounded if not used.
ANLB	I	16	Analog Loopback Control Input. Must be set to logic '0' for normal operation. When pulled to logic '1', the transmit filter input is disconnected from the output of the transmit preamplifier and connected to the VPO ⁺ output of the receive power amplifier.
GS _X	O	17	Analog output of the transmit input amplifier. Used to set gain externally.
VF _{XI} ⁻	I	18	Inverting input of the transmit input amplifier.
VF _{XI} ⁺	I	19	Non-inverting input of the transmit input amplifier.
V _{BB}	S	20	Negative Power Supply Pin. V _{BB} = -5V ±5%

(*) I: Input, O: Output, S: Power Supply.

TRI-STATE[®] is a trademark of National Semiconductor Corp.

FUNCTIONAL DESCRIPTION

POWER-UP

When power is first applied, power-on reset circuitry initializes the device and places it into the power-down mode. All non-essential circuits are deactivated and the D_X and V_{FRO} outputs are put in high impedance states. To power-up the device, a logical low level or clock must be applied to the $MCLK_R/PDN$ pin and FS_X and/or FS_R pulses must be present. Thus 2 power-down control modes are available. The first is to pull the $MCLK_R/PDN$ pin high; the alternative is to hold both FS_X and FS_R inputs continuously low. The device will power-down approximately 2 ms after the last FS_X pulse. The TRI-STATE PCM data output, D_X , will remain in the high impedance state until the second FS_X pulse.

SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to $MCLK_X$ and the $MCLK_R/PDN$ pin can be used as a power-down control. A low level on $MCLK_R/PDN$ powers up the device and a high level powers down the device. In either case, $MCLK_X$ will be selected as the master clock for both the transmit and receive circuits. A bit clock must also be applied to $BCLK_X$ and the $BCLK_R/CLKSEL$ can be used to select the proper internal divider for a master clock of 1.536 MHz, 1.544 MHz or 2.048 MHz. For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame.

With a fixed level on the $BCLK_R/CLKSEL$ pin, $BCLK_X$ will be selected as the bit clock for both the transmit and receive directions. Table 1 indicates the frequencies of operation which can be selected, depending on the state of $BCLK_R/CLKSEL$. In this synchronous mode, the bit clock, $BCLK_X$, may be from 64 kHz to 2.048 MHz, but must be synchronous with $MCLK_X$.

Table 1: Selection of Master Clock Frequencies.

BCLKR/CLKSEL	Master Clock Frequency Selected	
	ETC5067 ETC5067-X	ETC5064 ETC5064-X
Clocked	2.048MHz	1.536MHz or 1.544MHz
0	1.536MHz or 1.544MHz	2.048MHz
1 (or open circuit)	2.048MHz	1.536MHz or 1.544MHz

Each FS_X pulse begins the encoding cycle and the PCM data from the previous encode cycle is shift out of the enabled D_X output on the positive edge of $BCLK_X$. After 8 bit clock periods, the TRISTATE D_X output is returned to a high impedance state. With an FS_R pulse, PCM data is latched via the D_R input on the negative edge of $BCLK_X$ (or on $BCLK_R$ if running). FS_X and FS_R must be synchronous with $MCLK_X/R$.

ASYNCHRONOUS OPERATION

For asynchronous operation, separate transmit and receive clocks may be applied. $MCLK_X$ and $MCLK_R$ must be 2.048 MHz for the ETC5067 or 1.536 MHz, 1.544 MHz for the ETC5064, and need not be synchronous. For best transmission performance, however, $MCLK_R$ should be synchronous with $MCLK_X$, which is easily achieved by applying only static logic levels to the $MCLK_R/PDN$ pin. This will automatically connect $MCLK_X$ to all internal $MCLK_R$ functions (see pin description). For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame. FS_X starts each encoding cycle and must be synchronous with $MCLK_X$ and $BCLK_X$. FS_R starts each decoding cycle and must be synchronous with $BCLK_R$. $BCLK_R$ must be a clock, the logic levels shown in Table 1 are not valid in asynchronous mode. $BCLK_X$ and $BCLK_R$ may operate from 64kHz to 2.048 MHz.

SHORT FRAME SYNC OPERATION

The device can utilize either a short frame sync pulse or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses, FS_X and FS_R , must be one bit clock period long, with timing relationships specified in figure 2. With FS_X high during a falling edge of $BCLK_R$, the next rising edge of $BCLK_X$ enables the D_X TRI-STATE output buffer, which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the D_X output. With FS_R high during a falling edge of $BCLK_R$ ($BCLK_X$ in synchronous mode), the next falling edge of $BCLK_R$ latches in the sign bit. The following seven falling edges latch in the seven remaining bits. Both devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

LONG FRAME SYNC OPERATION

To use the long frame mode, both the frame sync pulses, FS_X and FS_R , must be three or more bit clock periods long, with timing relationships specified in figure 3. Based on the transmit frame sync FS_X , the device will sense whether short or long frame sync

pulses are being used. For 64 kHz operation, the frame sync pulses must be kept low for a minimum of 160 ns (see Fig 1). The D_X TRI-STATE output buffer is enabled with the rising edge of FS_X or the rising edge of BCLK_X, whichever comes later, and the first bit clocked out is the sign bit. The following seven BCLK_X rising edges clock out the remaining seven bits. The D_X output is disabled by the falling BCLK_X edge following the eighth rising edge, or by FS_X going low, whichever comes later. A rising edge on the receive frame sync pulse, FS_R, will cause the PCM data at D_R to be latched in on the next eight falling edges of BCLK_R (BCLK_X in synchronous mode). Both devices may utilize the long frame sync pulse in synchronous or asynchronous mode.

TRANSMIT SECTION

The transmit section input is an operational amplifier with provision for gain adjustment using two external resistors, see figure 4. The low noise and wide bandwidth allow gains in excess of 20 dB across the audio passband to be realized. The op amp drives a unity gain filter consisting of RC active pre-filter, followed by an eighth order switched-capacitor bandpass filter directly drives the encoder sample-and-hold circuit. The A/D is of companding type according to A-law (ETC5067 and ETC5067-X) or μ -law (ETC5064 and ETC5064-X) coding conventions. A precision voltage reference is trimmed in manufacturing to provide an input over load (t_{MAX}) of nominally 2.5V peak (see table of Transmission Characteristics). The FS_X frame sync pulse controls the sampling of the filter output, and then the successive-approximation encoding cycle begins. The 8-bit code is then loaded into a buffer and shifted out through D_X at the next FS_X pulse. the total encoding delay will be approximately 165 μ s (due to the transmit filter) plus 125 μ s (due to encoding delay), which totals 290 μ s. Any offset voltage due to the filters or comparator is cancelled by sign bit integration.

RECEIVE SECTION

The receive section consist of an expanding DAC which drives a fifth order switched-capacitor low pass filter clocked at 256kHz. The decoder is A-law (ETC5067 and ETC5067-X) or μ -law (ETC5064 and ETC5064-X) and the 5 th order low pass filter corrects for the sin x/x attenuation due to the 8kHz sample and hold. The filter is then followed by a 2 nd order RC active post-filter and power amplifier capable of driving a 600 Ω load to a level of 7.2dBm. The receive section is unity-gain. Upon the occurrence of FS_R, the data at the D_R input is clocked in on the falling edge of the next eight BCLK_R (BCLK_X) periods. At the end of the decoder time slot, the decoding cycle begins, and 10 μ s later the decoder DAC output is updated. The total decoder delay is about 10 μ s (decoder up-date) plus 110 μ s (filter delay) plus 62.5 μ s (1/2 frame), which gives approximately 180 μ s.

RECEIVE POWER AMPLIFIERS

Two inverting mode power amplifiers are provided for directly driving a matched line interface transformer. The gain of the first power amplifier can be adjusted to boost the \pm 2.5V peak output signal from the receive filter up \pm 3.3V peak into an unbalanced 300 Ω load, or \pm 4.0V into an unbalanced 15k Ω load. The second power amplifier is internally connected in unity-gain inverting mode to give 6dB of signal gain for balanced loads. Maximum power transfer to a 600 Ω subscriber line termination is obtained by differentially driving a balanced transformer with a $\sqrt{2} : 1$ turns ratio, as shown in figure 4. A total peak power of 15.6dBm can be delivered to the load plus termination. Both power amplifier can be powered down independently from the PDN input by connecting the VPI input to V_{BB} saving approximately 12 mW of power.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	V _{CC} to GNDA	7	V
V _{BB}	V _{BB} to GNDA	-7	V
V _{IN} , V _{OUT}	Voltage at any Analog Input or Output	V _{CC} +0.3 to V _{BB} -0.3	V
	Voltage at any Digital Input or Output	V _{CC} +0.3 to GNDA -0.3	V
T _{oper}	Operating Temperature Range: ETC5064/67 ETC5064-X/67-X	-25 to +125 -40 to +125	$^{\circ}$ C $^{\circ}$ C
T _{stg}	Storage Temperature Range	-65 to +150	$^{\circ}$ C
	Lead Temperature (soldering, 10 seconds)	300	$^{\circ}$ C

ETC5064 - ETC5064-X - ETC5067 - ETC5067-X

ELECTRICAL OPERATING CHARACTERISTICS

$V_{CC} = 5.0V \pm 5\%$, $V_{BB} = -5V \pm 5\%$, $GNDA = 0V$, $T_A = 0^\circ C$ to $70^\circ C$ (ETC5064-X/67-X: $T_A = -40^\circ C$ to $85^\circ C$), unless otherwise noted; typical characteristics specified at $V_{CC} = 5.0V$, $V_{BB} = -5.0V$, $T_A = 25^\circ C$; all signals are referenced to $GNDA$.

DIGITAL INTERFACE (All devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{IL}	Input Low Voltage			0.6	V
V_{IH}	Input High Voltage	2.2			V
V_{OL}	Output Low Voltage $I_L = 3.2 \text{ mA}$ $I_L = 3.2 \text{ mA}$, Open Drain			0.4	V
	$\frac{D_X}{TS_X}$			0.4	V
V_{OH}	Output High Voltage $I_H = 3.2 \text{ mA}$				V
	D_X	2.4			V
I_{IL}	Input Low Current ($GNDA \leq V_{IN} \leq V_{IL}$) all digital inputs Except $BCLK_R$	- 10		10	μA
I_{IH}	Input High Current ($V_{IH} \leq V_{IN} \leq V_{CC}$) Except $ANLB$	- 10		10	μA
I_{OZ}	Output Current in High Impedance State (TRI-STATE) ($GNDA \leq V_O \leq V_{CC}$)				μA
	D_X	- 10		10	μA

ANALOG INTERFACE WITH TRANSMIT INPUT AMPLIFIER (all devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit	
I_{IXA}	Input Leakage Current ($- 2.5 \text{ V} \leq V \leq + 2.5 \text{ V}$)	VF_{Xl}^+ or VF_{Xl}^-	- 200		200	nA
R_{IXA}	Input Resistance ($- 2.5 \text{ V} \leq V \leq + 2.5 \text{ V}$)	VF_{Xl}^+ or VF_{Xl}^-	10			M Ω
R_{OXA}	Output Resistance (closed loop, unity gain)		1	3		Ω
R_{LXA}	Load Resistance	GS_X	10			k Ω
C_{LXA}	Load Capacitance	GS_X		50		pF
V_{OXA}	Output Dynamic Range ($R_L \geq 10 \text{ k}\Omega$)	GS_X	- 2.8		+2.8	V
A_{VXA}	Voltage Gain (VF_{Xl}^+ to GS_X)		5000			V/V
F_{UXA}	Unity Gain Bandwidth		1	2		MHz
V_{OSXA}	Offset Voltage		- 20		20	mV
V_{CMXA}	Common-mode Voltage		- 2.5		2.5	V
$CMRR_{XA}$	Common-mode Rejection Ratio		60			dB
$PSRR_{XA}$	Power Supply Rejection Ratio		60			dB

ANALOG INTERFACE WITH RECEIVE FILTER (all devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit	
R_{ORF}	Output Resistance	VF_{RO}	1	3	Ω	
R_{LRF}	Load Resistance ($VF_{RO} = \pm 2.5 \text{ V}$)		10		k Ω	
C_{LRF}	Load Capacitance			25	pF	
$V_{OS_{RO}}$	Output DC Offset Voltage		- 200		200	mV

ELECTRICAL OPERATING CHARACTERISTICS (Continued)

ANALOG INTERFACE WITH POWER AMPLIFIERS (all devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit
IPI	Input Leakage Current ($-1.0\text{ V} \leq \text{VPI} \leq 1.0\text{ V}$)	- 100		100	nA
RPI	Input Resistance ($-1.0 \leq \text{VPI} \leq 1.0\text{ V}$)	10			M Ω
VIOS	Input Offset Voltage	- 25		25	mV
ROP	Output Resistance (inverting unity-gain at VPO^+ or VPO^-)		1		Ω
F _C	Unity-gain Bandwidth, Open Loop (VPO^-)		400		kHz
C _{LP}	Load Capacitance (VPO^+ or VPO^- to GNDA) R _L \geq 1500 Ω R _L = 600 Ω R _L = 300 Ω			100 500 1000	pF
GAp ⁺	Gain VPO^- to VPO^+ to GNDA, Level at $\text{VPO}^- = 1.77\text{ Vrms}$ (+ 3 dBmO)		- 1		V/V
PSRR _p	Power Supply Rejection of V _{CC} or V _{BB} (VPO^- connected to VPI) 0 kHz - 4 kHz 0 kHz - 50 kHz	60 36			dB

POWER DISSIPATION (all devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit
I _{CC0}	Power-down Current at ETC6064/67 ETC5064-X/67-X		0.5 0.5	1.5	mA mA
I _{BB0}	Power-down Current at ETC6064/67 ETC5064-X/67-X		0.05 0.05	0.3 0.4	mA mA
I _{CC1}	Active Current at ETC6064/67 ETC5064-X/67-X		7.0 7.0	10.0 12.0	mA mA
I _{BB1}	Active Current at ETC6064/67 ETC5064-X/67-X		7.0 7.0	10.0 12.0	mA mA

All TIMING SPECIFICATIONS

Symbol	Parameter	Min.	Typ.	Max.	Unit
1/t _{PM}	Frequency of master clocks MCLK _X and MCLK _R Depends on the device used and the BCLK _R /CLKSEL Pin		1.536 2.048 1.544		MHz
t _{WMH}	Width of Master Clock High MCLK _X and MCLK _R	160			ns
t _{WML}	Width of Master Clock Low MCLK _X and MCLK _R	160			ns
t _{RM}	Rise Time of Master Clock MCLK _X and MCLK _R			50	ns
t _{FM}	Fall Time of Master Clock MCLK _X and MCLK _R			50	ns
t _{PB}	Period of Bit Clock	485	488	15.725	ns
t _{WBH}	Width of Bit Clock High (V _{IH} = 2.2 V)	160			ns
t _{WBL}	Width of Bit Clock Low (V _{IL} = 0.6 V)	160			ns
t _{RB}	Rise Time of Bit Clock (t _{PB} = 488 ns)			50	ns
t _{FB}	Fall Time of Bit Clock (t _{PB} = 488 ns)			50	ns
t _{SBFM}	Set-up time from BCLK _X high to MCLK _X falling edge. (first bit clock after the leading edge of FS _X)	100			ns
t _{HBF}	Holding Time from Bit Clock Low to the Frame Sync (long frame only)	0			ns
t _{SFB}	Set-up Time from Frame Sync to Bit Clock (long frame only)	80			ns
t _{HBF1}	Hold Time from 3rd Period of Bit Clock Low to Frame Sync (long frame only) FS _X or FS _R	100			ns
t _{DZF}	Delay Time to valid data from FS _X or BCLK _X , whichever comes later and delay time from FS _X to data output disabled (C _L = 0 pF to 150 pF)	20		165	ns
t _{DBD}	Delay Time from BCLK _X high to data valid (load = 150 pF plus 2 LSTTL loads)	0		150	ns
t _{DZC}	Delay Time from BCLK _X low to data output disabled	50		165	ns
t _{SDB}	Set-up Time from D _R valid to BCLK _{R/X} low	50			ns
t _{HBD}	Hold Time from BCLK _{R/X} low to D _R invalid	50			ns
t _{HOLD}	Holding Time from Bit Clock High to Frame Sync (short frame only)	0			ns
t _{SF}	Set-up Time from FS _{X/R} to BCLK _{X/R} Low (short frame sync pulse) - Note 1	80			ns
t _{HF}	Hold Time from BCLK _{X/R} Low to FS _{X/R} Low (short frame sync pulse) - Note 1	100			ns
t _{XDP}	Delay Time to TS _X low (load = 150 pF plus 2 LSTTI loads)			140	ns
t _{WFL}	Minimum Width of the Frame Sync Pulse (low level) (64 bit/s operating mode)	160			ns

Note : 1.For short frame sync timing, FS_X and FS_R must go high while their respective bit clocks are high.

Figure 1 : 64 k bits/s TIMING DIAGRAM. (see next page for complete timing)

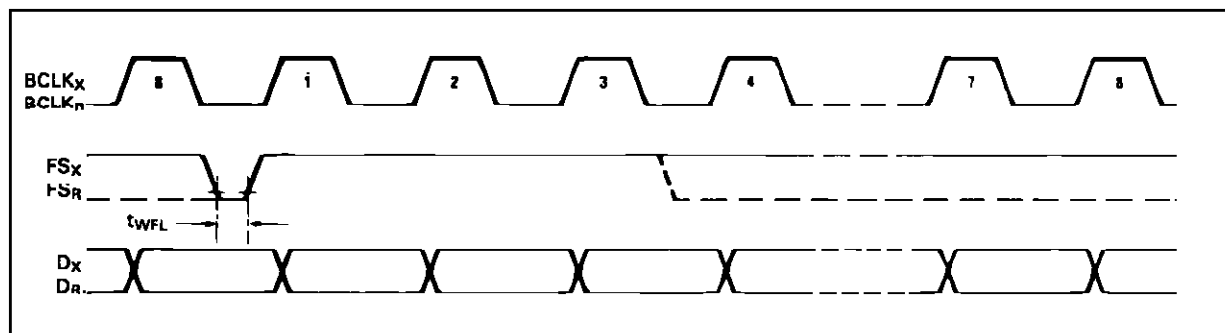


Figure 2 : Short Frame Sync Timing.

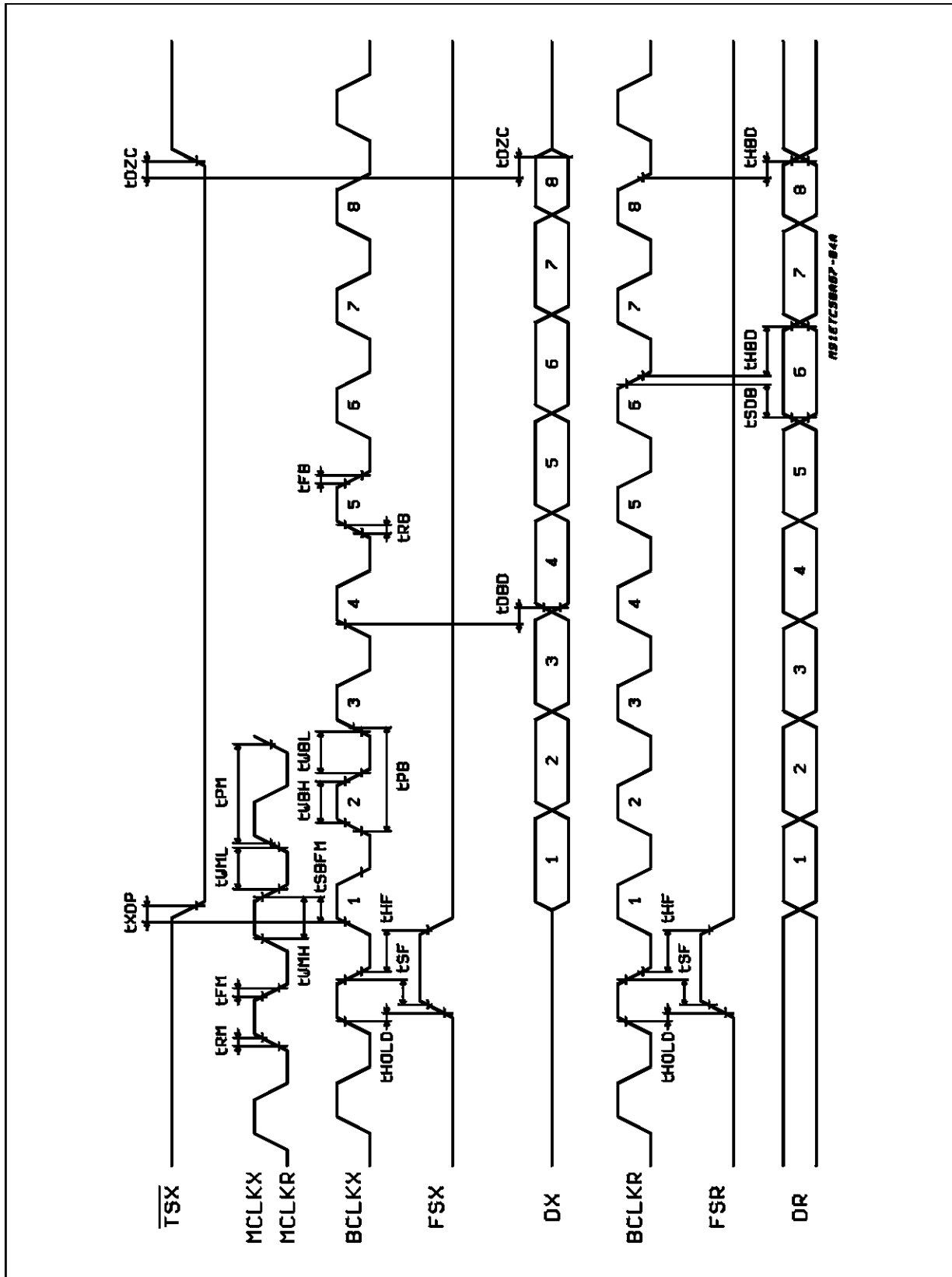
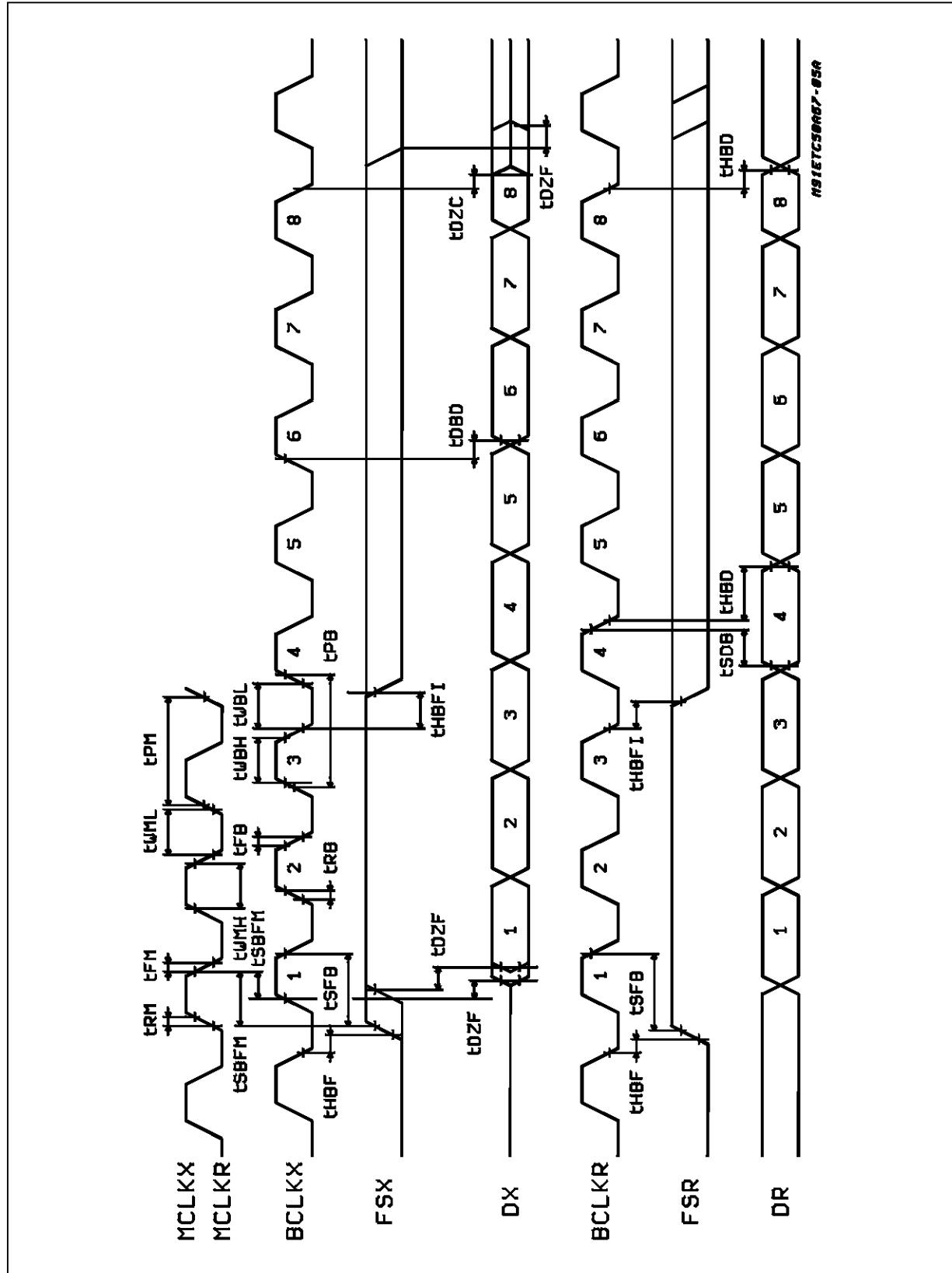


Figure 3 : Long Frame Sync Timing.



TRANSMISSION CHARACTERISTICS

(all devices) $T_A = 0^\circ\text{C}$ to 70°C (ETC5064-X/67-X: $T_A = -40^\circ\text{C}$ to 85°C), $V_{CC} = 5\text{V} \pm 5\%$, $V_{BB} = -5\text{V} \pm 5\%$, $G_{NDA} = 0\text{V}$, $f = 1.02\text{kHz}$, $V_{IN} = 0\text{dBm0}$ transmit input amplifier connected for unity-gain non-inverting. (unless otherwise specified).

AMPLITUDE RESPONSE

Symbol	Parameter	Min.	Typ.	Max.	Unit
	Absolute Levels - Nominal 0 dBm0 is 4 dBm (600Ω). 0 dBm0		1.2276		Vrms
t _{MAX}	Max Overload Level 3.14 dBm0 3.17 dBm0 ETC5067 ETC5064		2.492 2.501		VPK
G _{XA}	Transmit Gain, Absolute ($T_A = 25^\circ\text{C}$, $V_{CC} = 5\text{V}$, $V_{BB} = -5\text{V}$) Input at $G_{SX} = 0\text{dBm0}$ at 1020Hz	-0.15		0.15	dB
G _{XR}	Transmit Gain, Relative to G _{XA} f = 16Hz f = 50Hz f = 60Hz f = 180Hz f = 200Hz f = 300Hz -3000Hz f = 3200Hz (ETC5064-X/67-X) f = 3300Hz f = 3400Hz f = 4000Hz f = 4600Hz and up, measure response from 0Hz to 4000Hz	- - - -2.8 -1.8 -0.15 -0.35 -0.35 -0.7		-40 -30 -26 -0.2 -0.1 0.15 0.20 0.05 0 -14 -32	dB
G _{XAT}	Absolute Transmit Gain Variation with Temperature $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$ $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (ETC5064-X/67-X)	-0.1 -0.15		0.1 0.15	dB
G _{XAV}	Absolute Transmit Gain Variation with Supply Voltage ($V_{CC} = 5\text{V} \pm 5\%$, $V_{BB} = -5\text{V} \pm 5\%$)	-0.05		0.05	dB
G _{XRL}	Transmit Gain Variation with Level Sinusoidal Test Method Reference Level = -10dBm0 $V_{FXL}^+ = -40\text{dBm0}$ to $+3\text{dBm0}$ $V_{FXL}^+ = -50\text{dBm0}$ to -40dBm0 $V_{FXL}^+ = -55\text{dBm0}$ to -50dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB
G _{RA}	Receive Gain, Absolute ($T_A = 25^\circ\text{C}$, $V_{CC} = 5\text{V}$, $V_{BB} = -5\text{V}$) Input = Digital Code Sequence for 0dBm0 Signal at 1020Hz	-0.15		0.15	dB
G _{RR}	Receive Gain, Relative to G _{RA} f = 0Hz to 3000Hz f = 3200Hz (ETC5064-X/67-X) f = 3300Hz f = 3400Hz f = 4000Hz	-0.15 -0.35 -0.35 -0.7		0.15 0.20 0.05 0 -14	dB
G _{RAT}	Absolute Receive Gain Variation with Temperature $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$ $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (ETC5064-X/67-X)	-0.1 -0.15		0.1 0.15	dB
G _{RAV}	Absolute Receive Gain Variation with Supply Voltage ($V_{CC} = 5\text{V} \pm 5\%$, $V_{BB} = -5\text{V} \pm 5\%$)	-0.05		0.05	dB
G _{RRL}	Receive Gain Variation with Level Sinusoidal Test Method; Reference Input PCM code corresponds to an ideally encoded -10dBm0 signal PCM level = -40dBm0 to +3dBm0 PCM level = -50dBm0 to -40dBm0 PCM level = -55dBm0 to -50dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB
V _{RO}	Receive Filter Output at V_{RO} $R_L = 10\text{k}\Omega$	-2.5		2.5	V

ETC5064 - ETC5064-X - ETC5067 - ETC5067-X

TRANSMISSION CHARACTERISTICS (continued). ENVELOPE DELAY DISTORTION WITH FREQUENCY

Symbol	Parameter	Min.	Typ.	Max.	Unit
D _{XA}	Transmit Delay, Absolute (f = 1600 Hz)		290	315	μs
D _{XR}	Transmit Delay, Relative to D _{XA} f = 500 Hz-600 Hz f = 600 Hz-800 Hz f = 800 Hz-1000 Hz f = 1000 Hz-1600 Hz f = 1600 Hz-2600Hz f = 2600 Hz-2800 Hz f = 2800 Hz-3000 Hz		195 120 50 20 55 80 130	220 145 75 40 75 105 155	μs
D _{RA}	Receive Delay, Absolute (f = 1600 Hz)		180	200	μs
D _{RR}	Receive Delay, Relative to D _{RA} f = 500 Hz-1000 Hz f = 1000 Hz-1600 Hz f = 1600 Hz-2600 Hz f = 2600 Hz-2800 Hz f = 2800 Hz-3000 Hz	- 40 - 30	- 25 - 20 70 100 145	90 125 175	μs

NOISE

Symbol	Parameter	Min.	Typ.	Max.	Unit
N _{XP}	Transmit Noise, P Message (A-LAW, VF _{XI} ⁺ = 0 V) Weighted 1) ETC5064 ETC5064-X		- 74 - 74	- 69 - 67	dBm0p dBm0p
N _{RP}	Receive Noise, P Message Weighted (A-LAW, PCM Code Equals Positive Zero)		- 82	- 79	dBm0p
N _{XC}	Transmit Noise, C Message Weighted (μ-LAW, VF _{XI} ⁺ = 0 V) ETC5064 ETC5064-X		12 12	15 16	dBrnC0 dBrnC0
N _{RC}	Receive Noise, C Message Weighted (μ-LAW, PCM Code Equals Alternating Positive and Negative Zero)		8	11	dBrnC0
N _{RS}	Noise, Single Frequency f = 0 kHz to 100 kHz, Loop around Measurement, VF _{XI} ⁺ = 0 V			- 53	dBm0
PPSR _X	Positive Power Supply Rejection, Transmit (note 2) V _{CC} = 5.0 V _{DC} + 100 mVrms, f = 0 kHz-50 kHz	40			dBp
NPSR _X	Negative Power Supply Rejection, Transmit (note 2) V _{BB} = 5.0 V _{DC} + 100 mVrms, f = 0 kHz-50 kHz	40			dBp
PPSR _R	Positive Power Supply Rejection, Receive (PCM code equals positive zero, V _{CC} = 5.0 V _{DC} + 100 mVrms) f = 0 Hz-4000Hz A LAW μ LAW f = 4 kHz-25 kHz f = 25 kHz-50 kHz	40 40 40 36			dBp dBc dB dB
NPSR _R	Negative Power Supply Rejection, Receive (PCM code equals positive zero, V _{BB} = - 5.0 V _{DC} + 100 mVrms) f = 0 Hz-4000Hz A LAW μ LAW f = 4 kHz-25 kHz f = 25 kHz-50 kHz	40 40 40 36			dBp dBc dB dB
SOS	Spurious out-of-band Signals at the Channel Output 0 dBm0, 300 Hz-3400 Hz input PCM applied at D _R 4600 Hz-7600 Hz 7600 Hz-8400 Hz 8400 Hz-100,000 Hz			-32 -40 -32	dB dB dB

TRANSMISSION CHARACTERISTICS (continued).

DISTORTION

Symbol	Parameter	Min.	Typ.	Max.	Unit
STD _X or STD _R	Signal to Total Distortion (sinusoidal test method)				
	Transmit or Receive Half-channel				dBp (ALAW)
	Level = 3.0 dBm0	33			
	= 0 dBm0 to – 30 dBm0	36			
	= – 40 dBm0	XMT 29			dBc (μLAW)
		RCV 30			
	= – 55 dBm0	XMT 14			
		RCV 15			
SFD _X	Single Frequency Distortion, Transmit (T _A = 25°C)			– 46	dB
SFD _R	Single Frequency Distortion, Receive (T _A = 25°C)			– 46	dB
IMD	Intermodulation Distortion Loop Around Measurement, VF _{XI} ⁺ = – 4 dBm0 to – 21 dBm0, two Frequencies in the Range 300 Hz-3400 Hz			– 41	dB

CROSSTALK

Symbol	Parameter	Min.	Typ.	Max.	Unit
CT _{X-R}	Transmit to Receive Crosstalk, 0dBm0 Transmit f = 300 Hz-3400 Hz, D _R = Steady PCM Code		– 90	– 75	dB
				– 65	dB
CT _{R-X}	Receive to Transmit Crosstalk, 0dBm0 Receive Level (note 2) f = 300 Hz-3400 Hz, VF _{XI} = 0 V		– 90	– 70	dB
				– 65	dB

POWER AMPLIFIERS

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{OL}	Maximum 0 dBm0 Level for Better than ± 0.1 dB Linearity Over the Range 10 dBm0 to + 3 dBm0 (balanced load, R _L connected between VPO ⁺ and VPO [–]) R _L = 600 Ω R _L = 1200 Ω R _L = 30 kΩ	33 3.5 4.0			Vrms
S/D _P	Signal/Distortion R _L = 600 Ω, 0 dBm0	50			dB

- Notes :** 1. Measured by extrapolation from the distortion test results.
2. PPSRX, NPSRX, CTR–X measured with a –50dBm0 activating signal applied at VF_{XI}⁺

ENCODING FORMAT AT D_X OUTPUT

	A-Law (Including even bit inversion)	μLaw
V _{IN} (at GS _X) = + Full-scale	1 0 1 0 1 0 1 0	1 0 0 0 0 0 0 0
V _{IN} (at GS _X) = 0 V	1 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1	1 1 1 1 1 1 1 1 0 1 1 1 1 1 1 1
V _{IN} (at GS _X) = – Full-scale	0 0 1 0 1 0 1 0	0 0 0 0 0 0 0 0

APPLICATION INFORMATION

POWER SUPPLIES

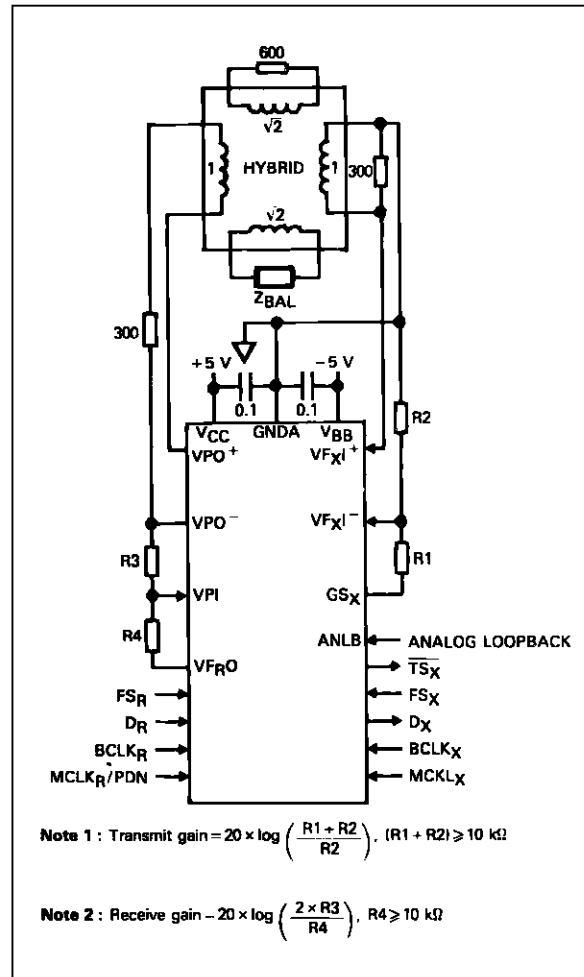
While the pins at the ETC506X family are well protected against electrical misuse, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed circuit board may be plugged into a "hot" socket with power and clocks already present, an extra long ground pin in the connector should be used.

All ground connections to each device should meet at a common point as close as possible to the GNDA pin. This minimizes the interaction of ground return currents flowing through a common bus impedance. 0.1µF supply decoupling capacitors should be connected from this common ground point to VCC and VBB as close to the device as possible.

For best performance, the ground point of each CODEC/FILTER on a card should be connected to a common card ground in star formation, rather than via a ground bus. This common ground point should be decoupled to VCC and VBB with 10µF capacitors.

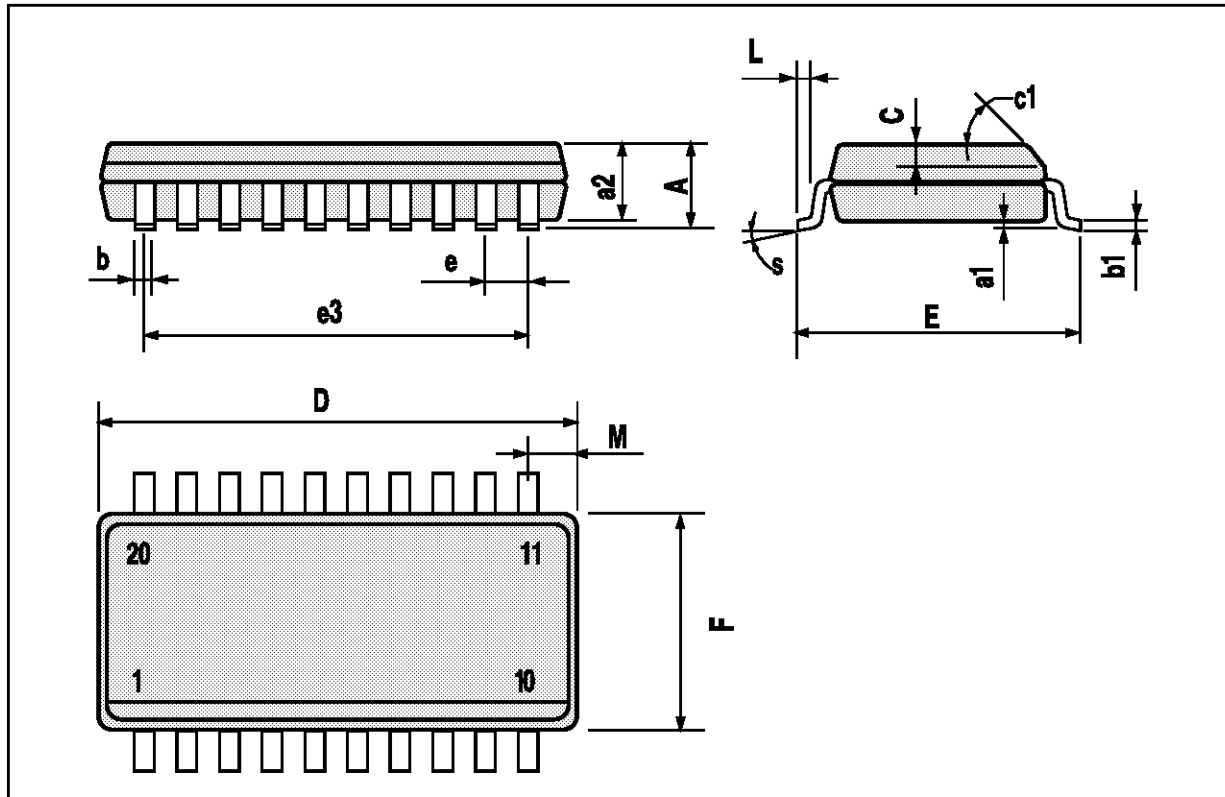
For best performance, \overline{TSx} should be grounded if not used.

Figure 4 : Typical Asynchronous Application.



SO20 PACKAGE MECHANICAL DATA

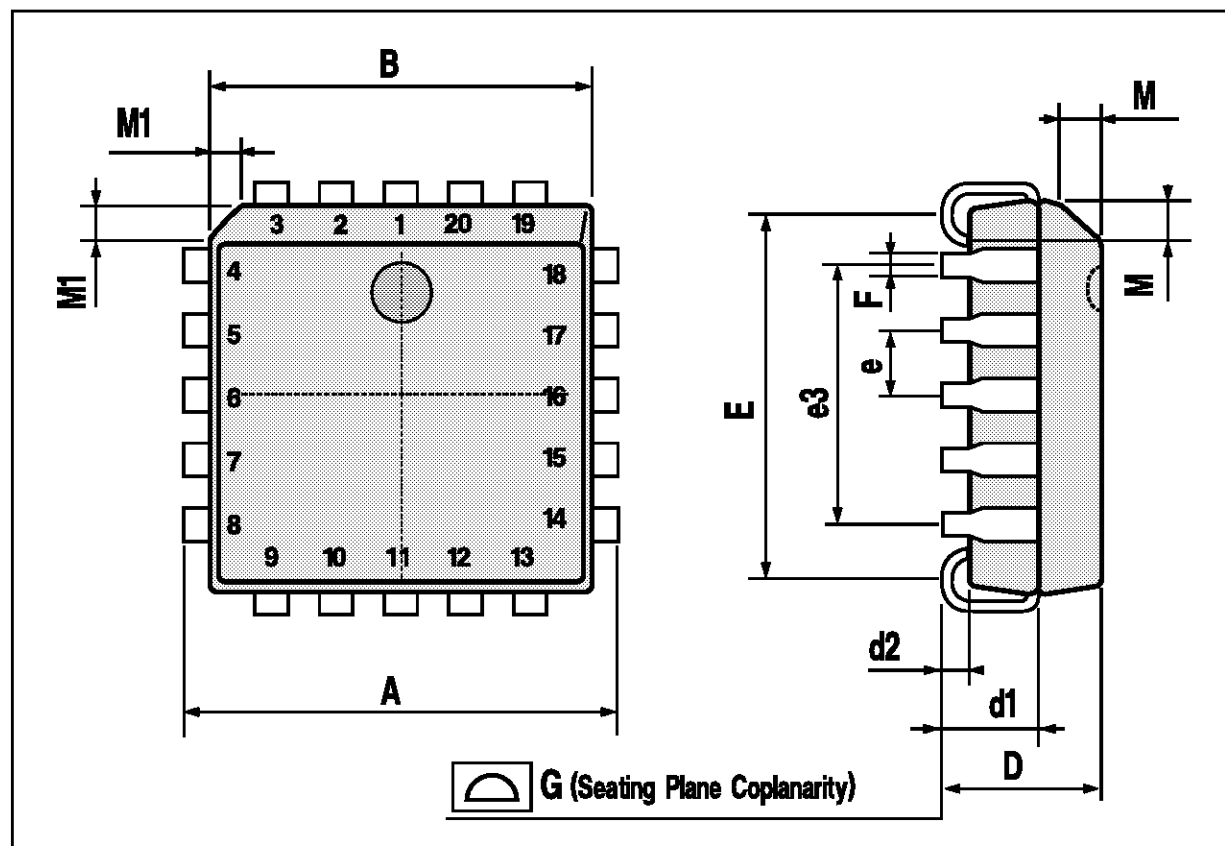
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			2.65			0.104
a1	0.1		0.2	0.004		0.008
a2			2.45			0.096
b	0.35		0.49	0.014		0.019
b1	0.23		0.32	0.009		0.013
C		0.5			0.020	
c1	45° (typ.)					
D	12.6		13.0	0.496		0.510
E	10		10.65	0.394		0.419
e		1.27			0.050	
e3		11.43			0.450	
F	7.4		7.6	0.291		0.300
L	0.5		1.27	0.020		0.050
M			0.75			0.030
S	8° (max.)					



ETC5064 - ETC5064-X - ETC5067 - ETC5067-X

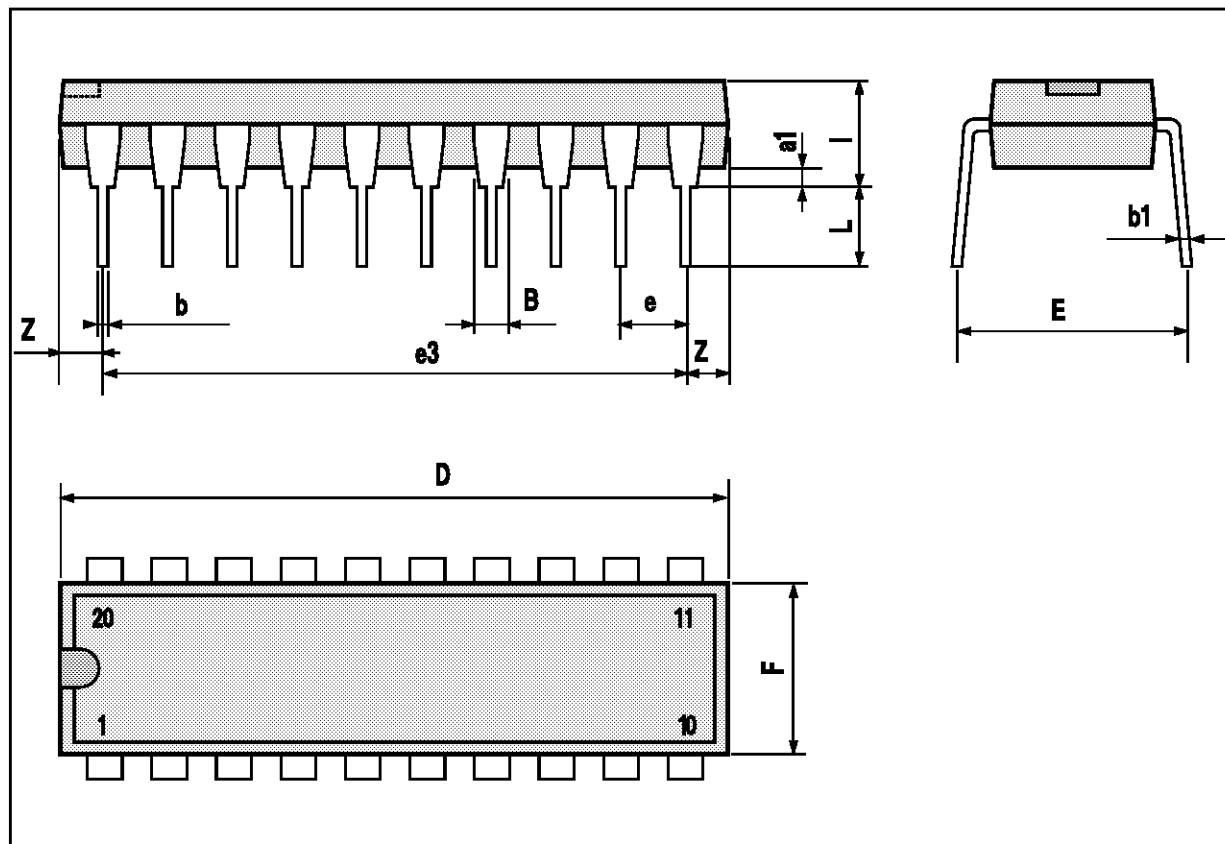
PLCC20 PACKAGE MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	9.78		10.03	0.385		0.395
B	8.89		9.04	0.350		0.356
D	4.2		4.57	0.165		0.180
d1		2.54			0.100	
d2		0.56			0.022	
E	7.37		8.38	0.290		0.330
e		1.27			0.050	
e3		5.08			0.200	
F		0.38			0.015	
G			0.101			0.004
M		1.27			0.050	
M1		1.14			0.045	



DIP20 PACKAGE MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.254			0.010		
B	1.39		1.65	0.055		0.065
b		0.45			0.018	
b1		0.25			0.010	
D			25.4			1.000
E		8.5			0.335	
e		2.54			0.100	
e3		22.86			0.900	
F			7.1			0.280
l			3.93			0.155
L		3.3			0.130	
Z			1.34			0.053



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